



MJ N-Channel Enhancement Mode Power MOSFET

Description

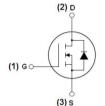
The MJ0205IA uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

General Features

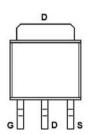
- V_{DS} =200V,I_D =5A
 R_{DS(ON)} <580mΩ @ V_{GS}=10V (Typ:520mΩ)
- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Fully characterized avalanche voltage and cur
 Excellent package for good heat dissipation

Application

- Power switching application
- Hard switched and high frequency circuits
- ◆ Uninterruptible power supply



Schematic diagram





Marking and pin assignment

TO-251 top view

Package Marking and Ordering Information

| Device Marking | Device | Device Package | Reel Size | Tape width | Quantity |
|----------------|----------|----------------|-----------|------------|----------|
| MJ0205IA | MJ0205IA | TO-251 | - | - | - |

Absolute Maximum Ratings (T_A=25℃ unless otherwise noted)

| Parameter | Symbol | Limit | Unit |
|--|----------|------------|------|
| Drain-Source Voltage | Vds | 200 | V |
| Gate-Source Voltage | Vgs | ±20 | V |
| Drain Current-Continuous | D | 5 | А |
| Drain Current-Pulsed (Note 1) | Ідм | 20 | А |
| Maximum Power Dissipation | PD | 30 | W |
| Operating Junction and Storage Temperature Range | Тј ,Тѕтс | -55 To 150 | °C |

Thermal Characteristic

| Thermal Resistance, Junction-to-Ambient (Note 2) | Reja | 4.17 | °C/W | |
|--|------|------|------|--|
|--|------|------|------|--|





Electrical Characteristics (T_A=25℃ unless otherwise noted)

| Parameter | Symbol | Condition | Min | Тур | Max | Unit |
|------------------------------------|-------------|--|-----|----------|----------|------|
| Off Characteristics | I | 1 | 1 | | 1 | |
| Drain-Source Breakdown Voltage | BVDSS | V _{GS} =0V I _D =250µA | 200 | - | - | V |
| Zero Gate Voltage Drain Current | loss | VDS=200V,VGS=0V | - | - | 1 | μA |
| Gate-Body Leakage Current | lgss | VDS=±20V,VDS=0V | - | - | ±100 | nA |
| On Characteristics (Note 3) | I | | | | | |
| Gate Threshold Voltage | VGS(th) | Vos=Vgs ,Io=250µA | 1.2 | 1.7 | 2.5 | V |
| Drain-Source On-State Resistance | Rds(on) | Vgs=10V, Id=2A | - | 520 | 580 | mΩ |
| Forward Transconductance | g fs | Vds=15V,Id=2A | - | 8 | - | S |
| Dynamic Characteristics (Note 4) | I | 1 | 1 | | 1 | |
| Input Capacitance | Clss | V _{DS} =25V,V _{GS} =0V F=1.0MHz | - | 580 | - | PF |
| Output Capacitance | Coss | | - | 90 | - | PF |
| Reverse Transfer Capacitance | Crss | | - | 3 | - | PF |
| Switching Characteristics (Note 4) | I | 1 | | 1 | | 1 |
| Turn-on Delay Time | td(on) | | - | 10 | - | nS |
| Turn-on Rise Time | tr | Vpp=100V Rt=150 | - | 12 | - | nS |
| Turn-Off Delay Time | td(off) | V _{DD} =100V, RL=15Ω V _{GS} =10V,R _G =2.5Ω | - | 15 | - | nS |
| Turn-Off Fall Time | tr | | - | 15 | - | nS |
| Total Gate Charge | Qg | - V _{DS} =100V,I _D =2A V _{GS} =10V | - | 12 | - | nC |
| Gate-Source Charge | Qgs | | - | 2.5 | - | nC |
| Gate-Drain Charge | Qgd | | - | 3.8 | - | nC |
| Drain-Source Diode Characteristics | | | | <u> </u> | <u> </u> | |
| Diode Forward Voltage (Note 3) | Vsd | V _{GS} =0V,Is=2A | - | - | 1.2 | V |
| Diode Forward Current (Note 2) | Is | | - | - | 5 | A |

Notes:

① Repetitive Rating: Pulse width limited by maximum junction temperature.

② Surface Mounted on FR4 Board, t \leq 10 sec.

③ Pulse Test: Pulse Width \leq 300µs, Duty Cycle \leq 2%.

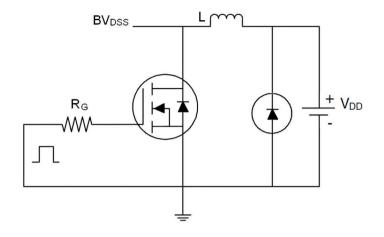
④ Guaranteed by design, not subject to production



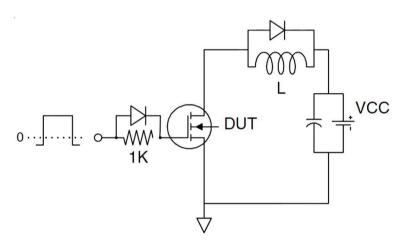




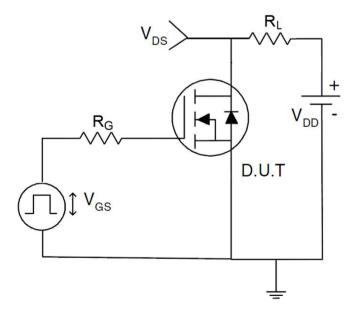
Test circuit







Gate charge test Circuit



Switch Time Test Circuit





Typical Electrical and Thermal Characteristics (Curves)

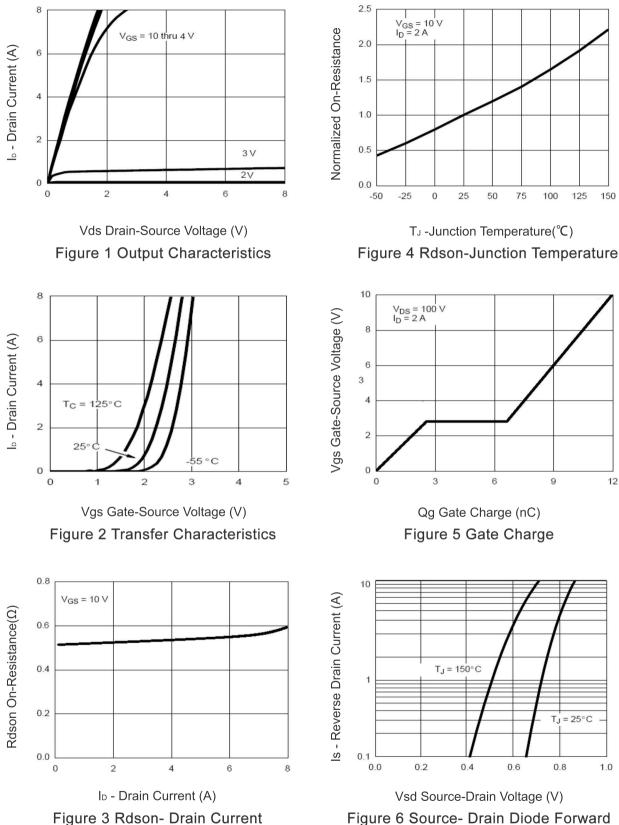
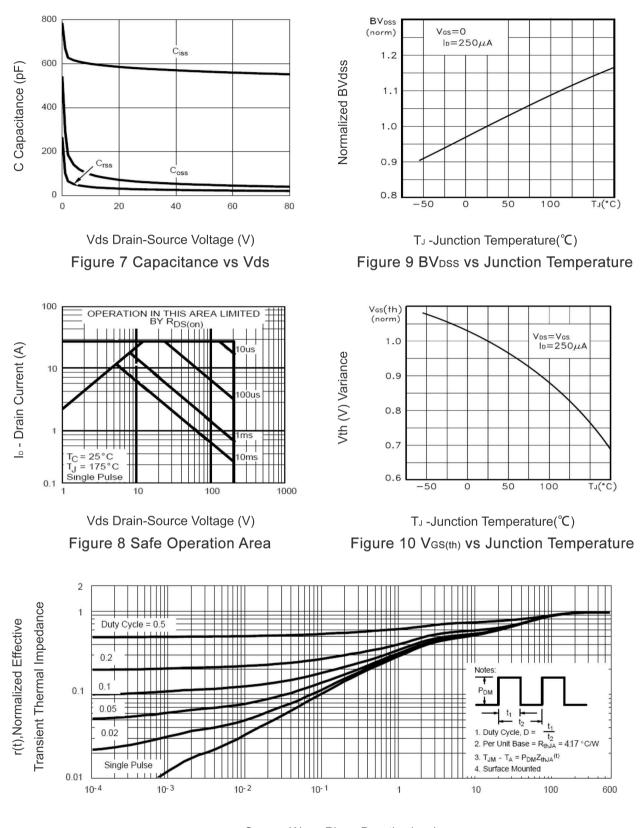


Figure 6 Source- Drain Diode Forward









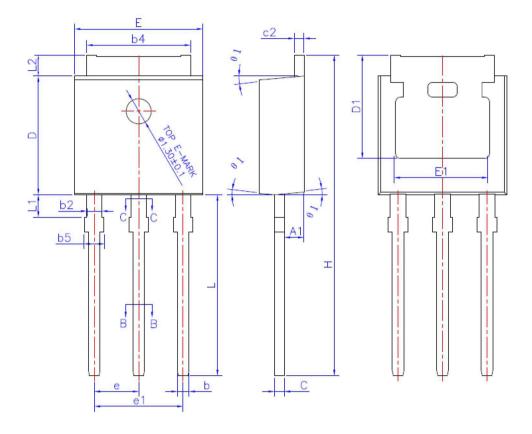
Square Wave Pluse Duration(sec) Figure 11 Normalized Maximum Transient Thermal Impedance





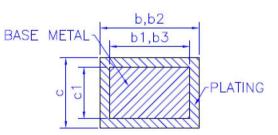


TO-251 Package Information



COMMON DIMENSIONS (UNITS OF MEASURE =MILLIMETER)

| SYMBOL | MIN | NOM | MAX |
|--------|-------|-------|-------|
| A | 2.20 | 2,30 | 2,35 |
| A1 | 0.90 | 1.01 | 1.10 |
| b | 0.56 | | 0.69 |
| b1 | 0.55 | 0.60 | 0.65 |
| b2 | 0.77 | | 0,90 |
| b3 | 0.76 | 0.81 | 0.86 |
| b4 | 5,23 | 5,33 | 5,43 |
| b5 | | | 1.05 |
| с | 0.46 | | 0,59 |
| c1 | 0.45 | 0.51 | 0,55 |
| c2 | 0.46 | | 0.59 |
| D | 6.00 | 6.10 | 6.20 |
| D1 | 5.20 | | - |
| E | 6,50 | 6,60 | 6,70 |
| E1 | 4.60 | 4.83 | 5.00 |
| е | 2,24 | 2,29 | 2,34 |
| e1 | 4.47 | 4.57 | 4.67 |
| Н | 16,18 | 16,48 | 16,78 |
| L | 9.00 | 9,30 | 9.60 |
| L1 | 0.95 | 1.16 | 1.35 |
| L2 | 0.90 | 1.08 | 1,25 |
| θ1 | 3° | 5° | 7° |
| θ2 | 1° | 3° | 5° |







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